PCN Number: 20220314002.1 PCN Date:										
Title: Qualification of Cu as an alternate bond wire for select devices										
Customer Contact: PCN Manager Dept: Quality Services										
Proposed 1 <sup>st</sup> Ship Date: Jun 10		5 20	2022					Date provided at		
Availability:   sample request					sample request					
	Change Type:					r Duran Cita				
Assembly Site			Design Data S			$\square$	Wafer Bump Site Wafer Bump Material			
Assembly Process Assembly Materials			Part number change				Wafer Bump Process			
				est Site						
			Test Pr				Wafer Fab Materials			
							Wafer Fab Process			
			PCN	Deta	ails					
Description of Change	e:									
This PCN is to inform of	the qualific	atio	n of an	altern	ate bond wire	e qu	ıalificat	ion as follows:		
Current	Bond Diam	nete	er	Add	itional Bond	d w	vire & diameter			
Au	, 1.3 mils				Cu, 0	.96	mil			
Reason for Change:										
Continuity of supply. 1) To align with world to	ochnology t	rond	de and	uco wi	ring with onb	200	od mod	shanical and		
electrical properties	echnology t	.i ent	us anu			anc	eu meu			
2) Maximize flexibility w	vithin our A	sser	nbly/Te	est pro	duction sites.					
3) Cu is easier to obtain			,.	•						
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):										
None										
Impact on Environmental Ratings										
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.										
RoHS	RoHS REACH		н	Green Statu			s IEC 62474			
🛛 No Change	🛛 No Change 🛛 🖾 No Change		9		🛛 No Change 🛛 🛛			No Change		
Changes to product identification resulting from this PCN:										
None										

Product Affected:					
UC2842AN	UC2844AN	UC3842ANG4	UC3844ANG4		
UC2842ANG4	UC2844ANG4	UC3842N	UC3844N		
UC2842N	UC2844N	UC3842NG4	UC3844NG4		
UC2842NG4	UC2845AN	UC3843AN	UC3845AN		
UC2843AN	UC2845ANG4	UC3843ANG4	UC3845ANG4		
UC2843ANG4	UC2845N	UC3843N	UC3845N		
UC2843N	UC2845NG4	UC3843NG4	UC3845NG4		
UC2843NG4	UC3842AN	UC3844AN			

TI Information Selective Disclosure



## Qualification Report Approve Date 11-MARCH -2022

Qualification Results

### Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: <u>UC2844N</u>	QBS Reference: <u>L293DNE</u>	QBS Reference: <u>NE5532P</u>	QBS Reference: <u>TS12A4514P</u>	QBS Reference: <u>UCC37322P</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	1/77/0	3/231/0
тс	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	3/225/0	-	1/77/0	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	-	1/77/0	3/231/0
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-

QBS: Qual By Similarity

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

#### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2108-005

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN ww admin team@list.ti.com

## **IMPORTANT NOTICE AND DISCLAIMER**

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF

# MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (<u>www.ti.com/legal/termsofsale.html</u>) or other applicable terms available either on <u>ti.com</u> or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.